

70591 U.S. PTO



03/28/97

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. 040679/0439

#3  
E. Hillis  
10-3-97

In re Patent Application of

Haruhiko MURATA et al.

Serial No. Unassigned

Filed: March 28, 1997

For: IMPROVEMENT IN OR RELATING TO CIRCUIT BOARD  
HAVING SOLDER BUMPS

CLAIM FOR CONVENTION PRIORITY

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

The benefit of the filing dates of the following prior foreign applications filed in the following foreign country is hereby requested, and the right of priority provided in 35 U.S.C. 119, is hereby claimed.

In support of this claim, filed herewith are certified copies of said original foreign applications:

Japanese Patent Applications

No. 8-076960 filed March 29, 1996;

No. 8-108287 filed April 26, 1996; and

No. 8-212845 filed August 12, 1996.

Respectfully submitted,

March 28, 1997

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